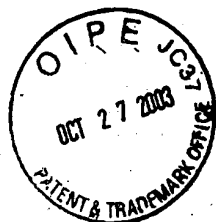
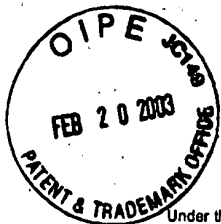


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		APPLICANT Satayadev R. Patel, et al.					
		FILING DATE 12/03/01		GROUP 2812			
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
NA	6,072,236	06/06/00	Akram, et al.				
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EXAMINER <i>W. H. V. G.</i>	DATE CONSIDERED <i>5/4/04</i>

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	10/005,308
		Filing Date	December 3, 2001
		First Named Inventor	PATEL et al.
		Art Unit	2812
		Examiner Name	
Sheet	1	of	3
		Attorney Docket Number	P19-US

U.S. PATENT DOCUMENTS					
Examiner Initials ¹	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
[Signature]	AA	US- 4,178,077	12-11-1979	TE VELDE	
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Examiner Signature	[Signature]	Date Considered	5/4/04
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¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 2 of 2

Complete if Known

Application Number	10/005,308
Filing Date	December 3, 2001
First Named Inventor	PATEL et al.
Group Art Unit	2812
Examiner Name	
Attorney Docket Number	P19-US

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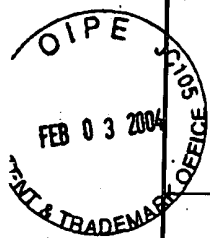
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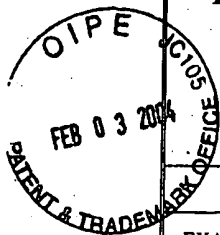
² Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

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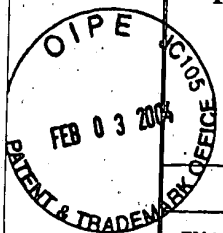
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PTO-1449		P19-US		10/005,308			
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		GROUP 2812					
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	5,726,480	03/10/98	Pister				
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<i>MA</i>	5,835,256	11/10/98	Huibers				
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<i>MA</i>	PCT-WO 99/49506, Filing date 16 March 1999						
EXAMINER	<i>Matthew C. [Signature]</i>		DATE CONSIDERED		5/4/04		

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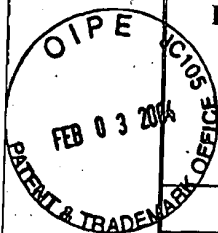
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EXAMINER: <i>[Signature]</i>			DATE CONSIDERED: 5/14/04				

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



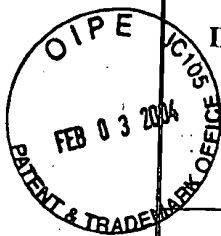
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		FILING DATE 12/03/01		GROUP 2812		
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<i>MS</i>	5,789,264	08/04/98	Chung			
	5,822,109	10/13/98	Jeon			
	5,834,163	11/10/98	Min, et al.			
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EXAMINER <i>Walter R. [Signature]</i>			DATE CONSIDERED <i>5/4/04</i>			

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INFORMATION DISCLOSURE CITATION		ATTY. DOCKET NO.		SERIAL NO.		
PTO-1449		P19-US		10/005,308		
SHEET 4 OF 6		APPLICANT Satayadev R. Patel, et al.		FILING DATE 12/03/01		
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1/A	5,930,025	07/27/99	Min			
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[Signature]			5/4/04			

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			APPLICANT Satayadev R. Patel; et al.				
			FILING DATE 12/03/01		GROUP 2812		
SHEET 5 OF 6							
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KS	Uthara Srinivasan et al., SELF-ASSEMBLED FLUOROCARBON FILM FOR ENHANCED STICTION REDUCTION, 1997, pp. 1399-1402.						
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INFORMATION DISCLOSURE CITATION PTO-1449 SHEET 6 OF 6		ATTY. DOCKET NO. P19-US		SERIAL NO. 10/005,308		
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
FOREIGN PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES NO
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